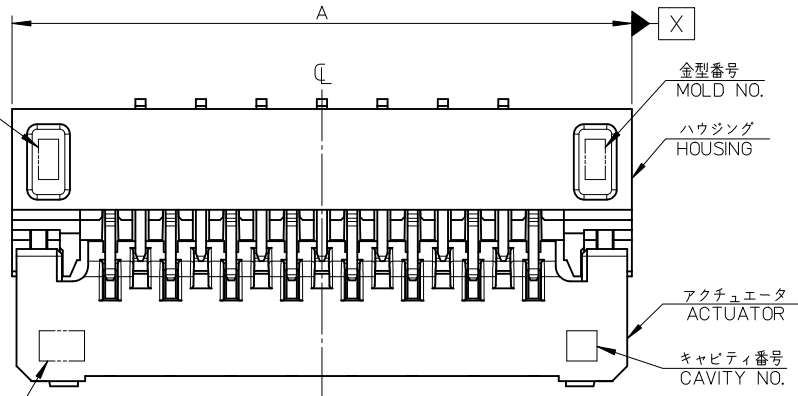


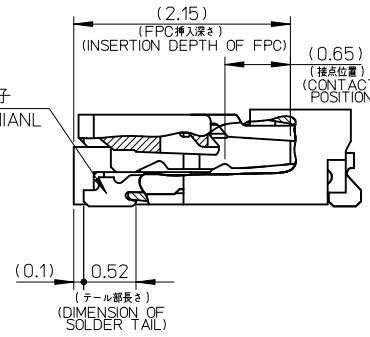
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キャビティ番号
CAVITY NO.

トレードマーク
TRADE MARK

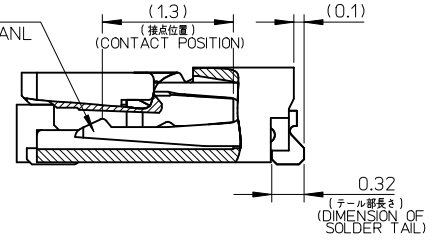


奇数極端子
ODD TERMINAL

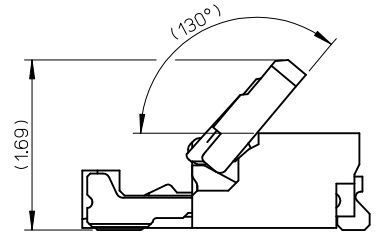
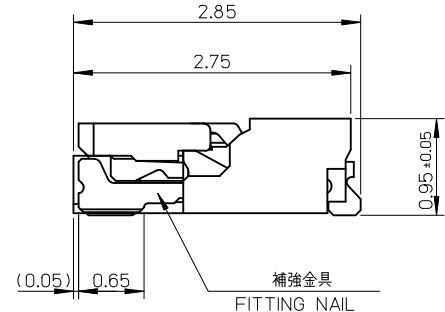
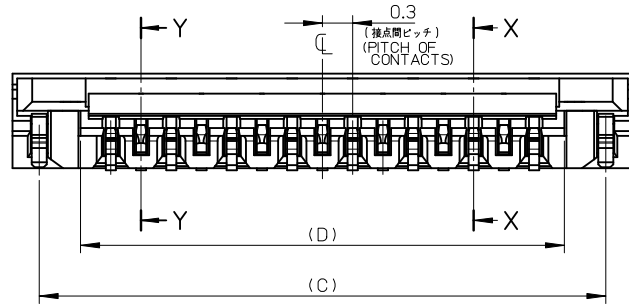


SECTION X-X

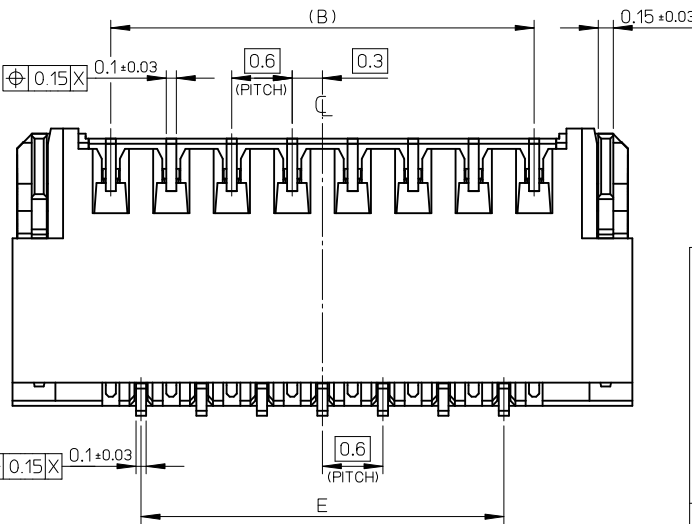
偶数極端子
EVEN TERMINAL



SECTION Y-Y

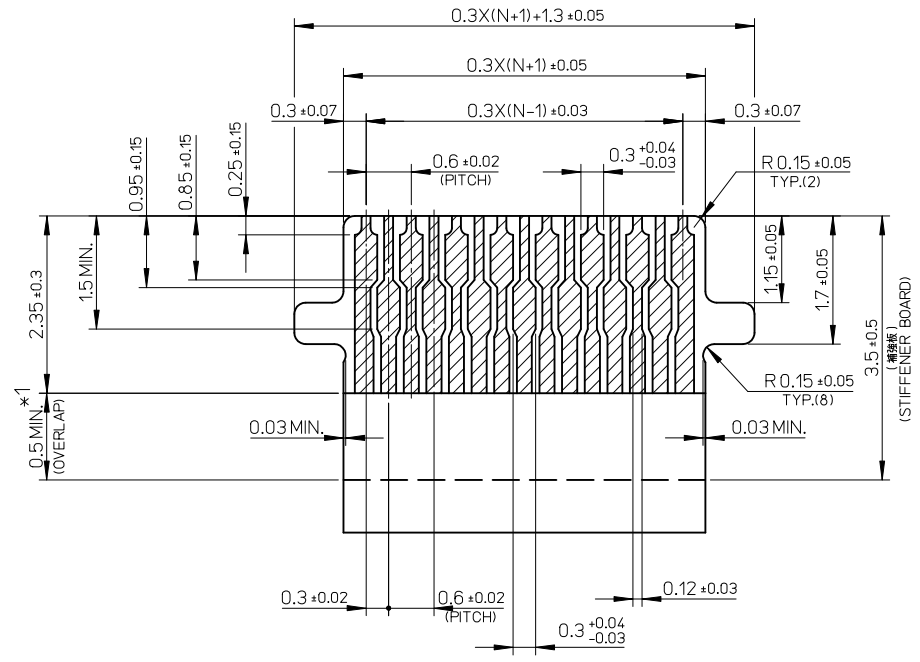
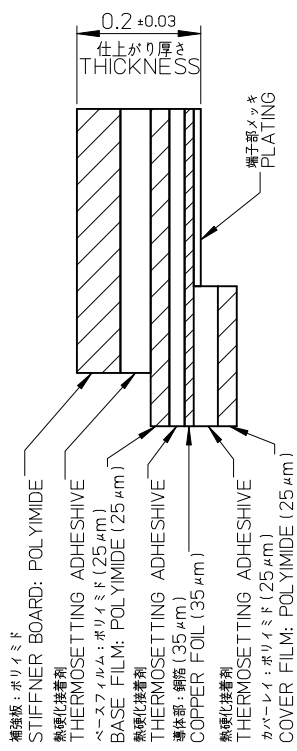


アクチュエータ開放位置
POSITION OF ACTUATOR OPEN

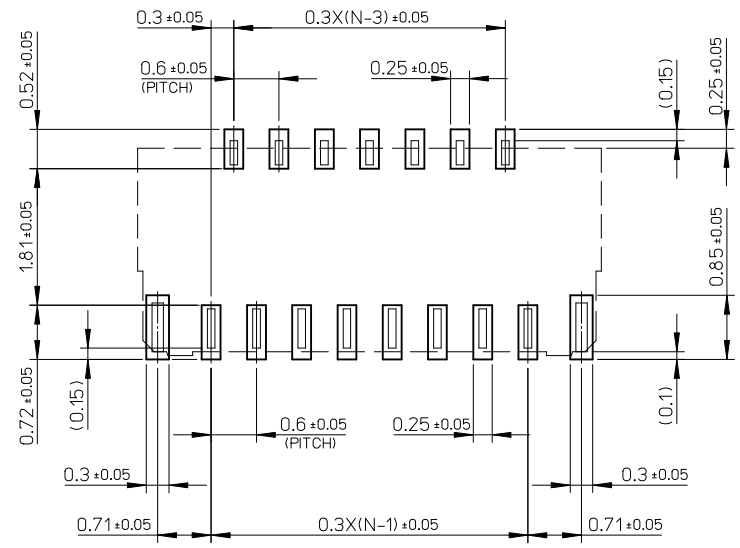


14.4	15.6	16.42	15.0	16.95	503566-5100	51
12.6	13.8	14.62	13.2	15.15	503566-4500	45
12.0	13.2	14.02	12.6	14.55	503566-4300	43
11.4	12.6	13.42	12.0	13.95	503566-4100	41
10.8	12.0	12.82	11.4	13.35	503566-3900	39
10.2	11.4	12.22	10.8	12.75	503566-3700	37
9.6	10.8	11.62	10.2	12.15	503566-3500	35
9.0	10.2	11.02	9.6	11.55	503566-3300	33
8.4	9.6	10.42	9.0	10.95	503566-3100	31
7.2	8.4	9.22	7.8	9.75	503566-2700	27
6.6	7.8	8.62	7.2	9.15	503566-2500	25
6.0	7.2	8.02	6.6	8.55	503566-2300	23
5.4	6.6	7.42	6.0	7.95	503566-2100	21
4.8	6.0	6.82	5.4	7.35	503566-1900	19
4.2	5.4	6.22	4.8	6.75	503566-1700	17
3.6	4.8	5.62	4.2	6.15	503566-1500	15
3.0	4.2	5.02	3.6	5.55	503566-1300	13
2.4	3.6	4.42	3.0	4.95	503566-1100	11
1.8	3.0	3.82	2.4	4.35	503566-0900	9
E	D	C	B	A	EMBOSSED PACKAGE	極数
					オーダー番号 ORDER NO.	CIRCUITS
CONNECTOR SERIES NO. 503566-***8						

REVISED EC NO.: J2011-1637 DRWN: HMIYAMOTO 2011/05/31 CHKD: H IJIMA 2011/05/31 APPR: KMORIKAWA 2011/06/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE _____		DESIGN UNITS METRIC		THIRD ANGLE PROJECTION		
	10 UNDER	± ---	DRAWN BY	DATE	TITLE						
	10 OVER 30 UNDER	± ---	CHECKED BY	DATE	0.3 FPC CONN E/O BTM CONTACT TYPE HGT=0.95MM						
	30 OVER	± ---	APPROVED BY	DATE							
ANGULAR ±1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. 503566-***8		MOLEX INCORPORATED		DOCUMENT NO. SD-503566-001		SHEET NO. 1 OF 2	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION											



適合するFPC推奨寸法 (参考)
APPLICABLE FPC
PATTERN DIMENSIONS(REF.)
(端子部仕上がり厚さ: 0.2±0.03)
(THICKNESS: 0.2±0.03)



参考基板レイアウト
RECOMMENDED PCB
PATTERN DIMENSIONS(REF.)

推奨ペースト厚 : 100µm
推奨マスク開口率 : 80%
RECOMMEND SCREEN THICKNESS : 100µm
RECOMMEND SCREEN OPEN RATIO : 80%

注記 NOTES

- 使用材料 MATERIALS
ハウジング : 液晶ポリマー (LCP)、ガラス充填、UL94V-0、ナチュラル (白色系)
アクチュエータ: ポリアミド (PA)、ガラス充填、UL94V-HB、黒色
奇数端子 : 燐青銅、ニッケル下地、金メッキ
偶数端子 : 燐青銅、ニッケル下地、金メッキ
補強金具 : 燐青銅、ニッケル下地、金メッキ
HOUSING : LIQUID CRYSTAL POLYMER(LCP), GLASS FILLED
UL94V-0, NATURAL(WHITE)
ACTUATOR : POLYAMIDE (PA), GLASS FILLED
UL94V-HB, BLACK
ODD TERMINAL : PHOSPHOR BRONZE, Gold OVER Nickel PLATING
EVEN TERMINAL: PHOSPHOR BRONZE, Gold OVER Nickel PLATING
FITTING NAIL : PHOSPHOR BRONZE, Gold OVER Nickel PLATING
- 端子、補強金具のコプラナリティは 0.1以下とする
COPLANALITY OF SOLDER TAILS AND FITTING NAILS: 0.1MAX.
- 一般公差: ± 0.3
GENERAL TOLERANCES: ±0.3
- ELV及びRoHS適合品
ELV AND RoHS COMPLIANT

FPC構成推奨仕様
STRUCTURE OF FPC

FPCについて (ABOUT FPC)

抜き方向は、導体側から補強板側を推奨します
補強板材質はポリイミド、接着剤は熱硬化接着剤を推奨します
なお、接着剤の接点部への付着は導通不良の原因となりますので
染み出しがないよう、お願いします

RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE
RECOMMENDED MATERIAL:
STIFFENER BOARD: POLYIMIDE
BONDING AGENT: THERMOSETTING ADHESIVE
PLEASE PLOT APPROPRIATE AMOUNT OF ADHESIVE ON
ADHEREND BECAUSE THERE IS A POSSIBILITY THAT
THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY

FPCパターンメッキ仕様

金メッキ: 0.1µm 以上
下地ニッケルメッキ: 2~6µm
FPC PATTERN PLATING
GOLD PLATING : 0.1µm MINIMUM
NICKEL UNDER PLATING : 2~6µm

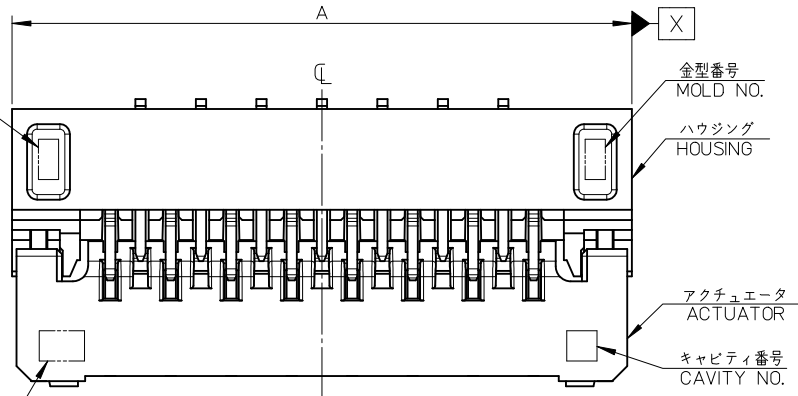
*1 補強板長さが図面通り確保できない場合は、カバーレイと補強板のオーバーラップ寸法を0.5mm以上としてください
WHEN STIFFENER BOARD DIMENSION CAN NOT BE SECURED AS DRAWING, PLEASE GIVE THE OVERLAP SIZE OF COVER FILM AND STIFFENER BOARD AS 0.5mm MINIMUM

SEE SHEET 1 OF 2 EC NO: J2011-1637 DRAWN: N. MIYAMOTO 2011/05/31 CHKD: H. IJIMA 2011/05/31 APPR: K. MORIKAWA 2011/06/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
			MM ONLY		METRIC	
	10 UNDER	± ---	DRAWN BY	DATE	TITLE	
	10 OVER 30 UNDER	± ---	H. IJIMA	2010/05/20	0.3 FPC CONN E/O BTM CONTACT TYPE HGT=0.95MM	
30 OVER	± ---	CHECKED BY	DATE	MOLEX INCORPORATED		
ANGULAR	±1 °	NMATSUURA	2010/05/20	MATERIAL NO. 503566-***8		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY	DATE	DOCUMENT NO. SD-503566-001		
		K. MORIKAWA	2010/06/11	SHEET NO. 2 OF 2		
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

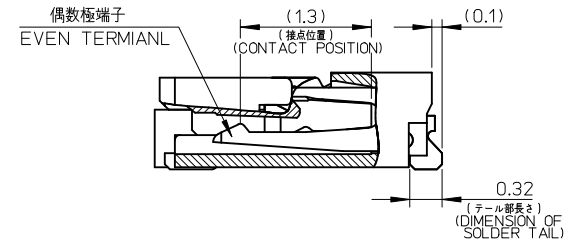
10 9 8 7 6 5 4 3 2 1

キャビティ番号
CAVITY NO.

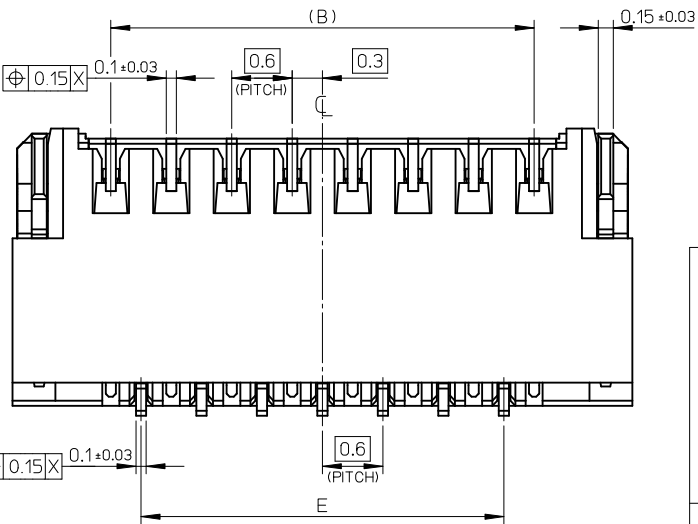
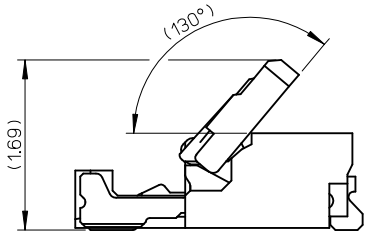
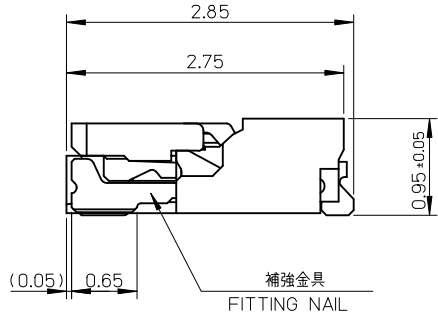
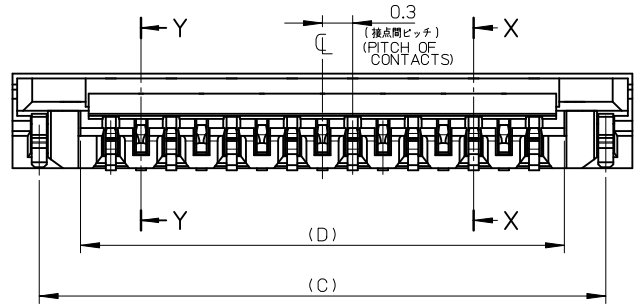
トレードマーク
TRADE MARK



SECTION X-X

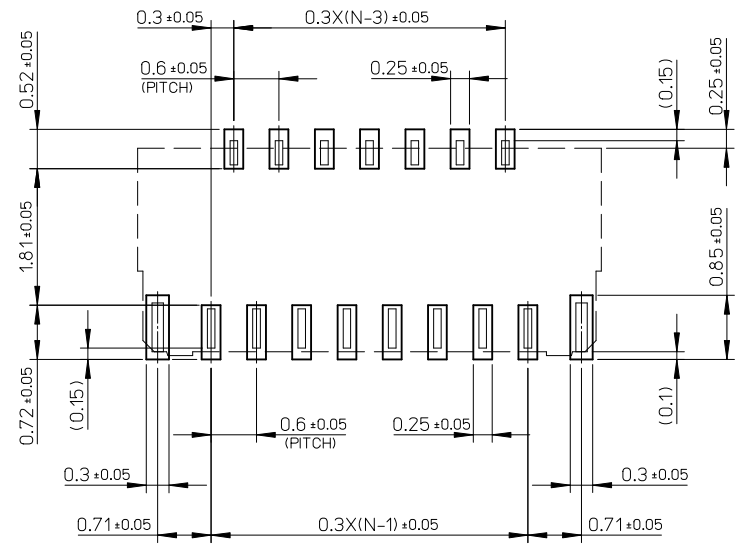
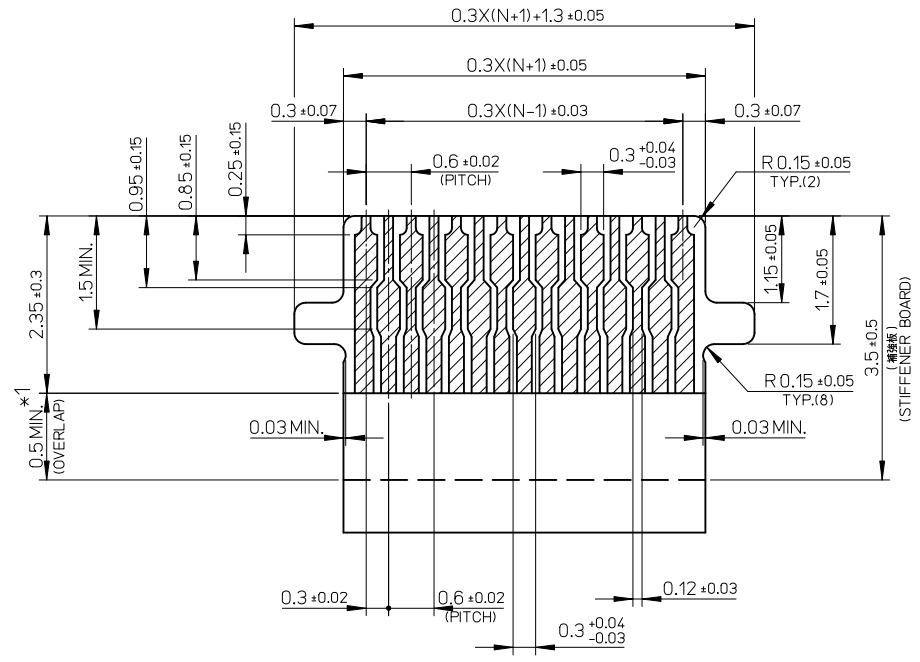
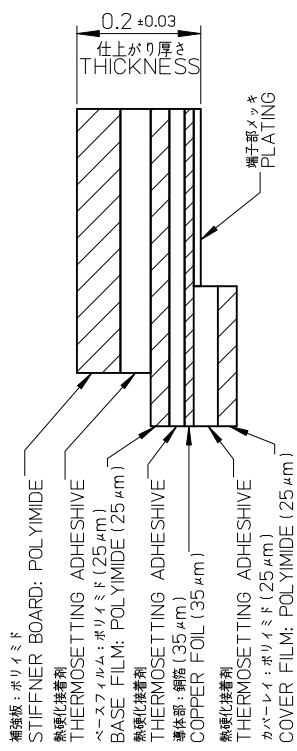


SECTION Y-Y



14.4	15.6	16.42	15.0	16.95	503566-5100	51
12.6	13.8	14.62	13.2	15.15	503566-4500	45
12.0	13.2	14.02	12.6	14.55	503566-4300	43
11.4	12.6	13.42	12.0	13.95	503566-4100	41
10.8	12.0	12.82	11.4	13.35	503566-3900	39
10.2	11.4	12.22	10.8	12.75	503566-3700	37
9.6	10.8	11.62	10.2	12.15	503566-3500	35
9.0	10.2	11.02	9.6	11.55	503566-3300	33
8.4	9.6	10.42	9.0	10.95	503566-3100	31
7.2	8.4	9.22	7.8	9.75	503566-2700	27
6.6	7.8	8.62	7.2	9.15	503566-2500	25
6.0	7.2	8.02	6.6	8.55	503566-2300	23
5.4	6.6	7.42	6.0	7.95	503566-2100	21
4.8	6.0	6.82	5.4	7.35	503566-1900	19
4.2	5.4	6.22	4.8	6.75	503566-1700	17
3.6	4.8	5.62	4.2	6.15	503566-1500	15
3.0	4.2	5.02	3.6	5.55	503566-1300	13
2.4	3.6	4.42	3.0	4.95	503566-1100	11
1.8	3.0	3.82	2.4	4.35	503566-0900	9
E	D	C	B	A	EMBOSSED PACKAGE	極数
					オーダー番号 ORDER NO.	CIRCUITS
CONNECTOR SERIES NO. 503566-***8						

REVISED EC NO.: J2011-1637 DRWN: HMIYAMOTO 2011/05/31 CHKD: HIJIMA 2011/05/31 APPR: KMORIKAWA 2011/06/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE		DESIGN UNITS METRIC		THIRD ANGLE PROJECTION		
	10 UNDER	± ---	DRAWN BY HIJIMA		DATE 2010/05/20		TITLE				
	10 OVER 30 UNDER	± ---	CHECKED BY NMATSUURA		DATE 2010/05/20		0.3 FPC CONN E/O BTM CONTACT TYPE HGT=0.95MM MOLEX INCORPORATED				
	30 OVER	± ---	APPROVED BY KMORIKAWA		DATE 2010/06/11						
	ANGULAR ±1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. 503566-***8		DOCUMENT NO. SD-503566-001		SHEET NO. 1 OF 2		
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION											



参考基板レイアウト
RECOMMENDED PCB
PATTERN DIMENSIONS(REF.)

推奨ペースト厚 : 100µm
推奨マスク開口率 : 80%
RECOMMEND SCREEN THICKNESS : 100µm
RECOMMEND SCREEN OPEN RATIO : 80%

適合するFPC推奨寸法 (参考)
APPLICABLE FPC
PATTERN DIMENSIONS(REF.)
(端子部仕上がり厚さ: 0.2±0.03)
(THICKNESS: 0.2±0.03)

注記 NOTES

- 使用材料 MATERIALS
ハウジング : 液晶ポリマー (LCP)、ガラス充填、UL94V-0、ナチュラル (白色系)
アクチュエータ: ポリアミド (PA)、ガラス充填、UL94V-HB、黒色
奇数端子 : 燐青銅、ニッケル下地、金メッキ
偶数端子 : 燐青銅、ニッケル下地、金メッキ
補強金具 : 燐青銅、ニッケル下地、金メッキ
HOUSING : LIQUID CRYSTAL POLYMER(LCP), GLASS FILLED
UL94V-0, NATURAL(WHITE)
ACTUATOR : POLYAMIDE (PA), GLASS FILLED
UL94V-HB, BLACK
ODD TERMINAL : PHOSPHOR BRONZE, Gold OVER Nickel PLATING
EVEN TERMINAL: PHOSPHOR BRONZE, Gold OVER Nickel PLATING
FITTING NAIL : PHOSPHOR BRONZE, Gold OVER Nickel PLATING
- 端子、補強金具のコプラナリティは 0.1以下とする
COPLANALITY OF SOLDER TAILS AND FITTING NAILS: 0.1MAX.
- 一般公差: ± 0.3
GENERAL TOLERANCES: ±0.3
- ELV及びRoHS適合品
ELV AND RoHS COMPLIANT

FPC構成推奨仕様
STRUCTURE OF FPC

FPCについて (ABOUT FPC)

抜き方向は、導体側から補強板側を推奨します
補強板材質はポリイミド、接着剤は熱硬化接着剤を推奨します
なお、接着剤の接点部への付着は導通不良の原因となりますので
染み出しがないよう、お願いします

RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE
RECOMMENDED MATERIAL:
STIFFENER BOARD: POLYIMIDE
BONDING AGENT: THERMOSETTING ADHESIVE
PLEASE PLOT APPROPRIATE AMOUNT OF ADHESIVE ON
ADHEREND BECAUSE THERE IS A POSSIBILITY THAT
THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY

FPCパターンメッキ仕様

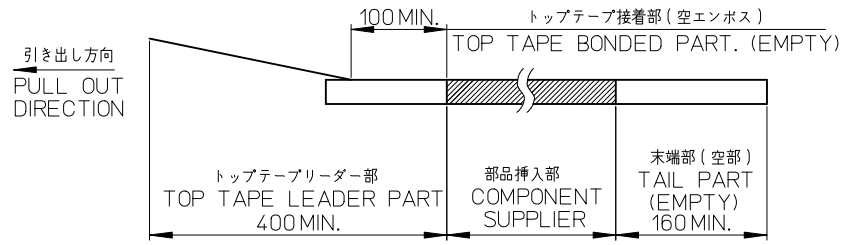
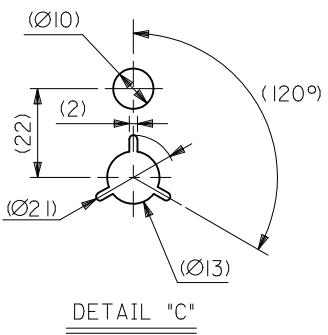
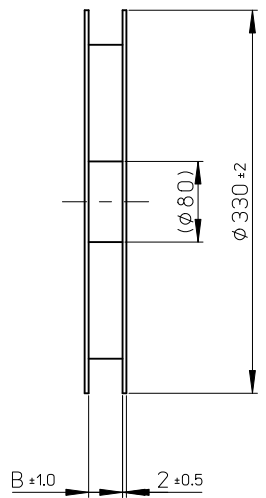
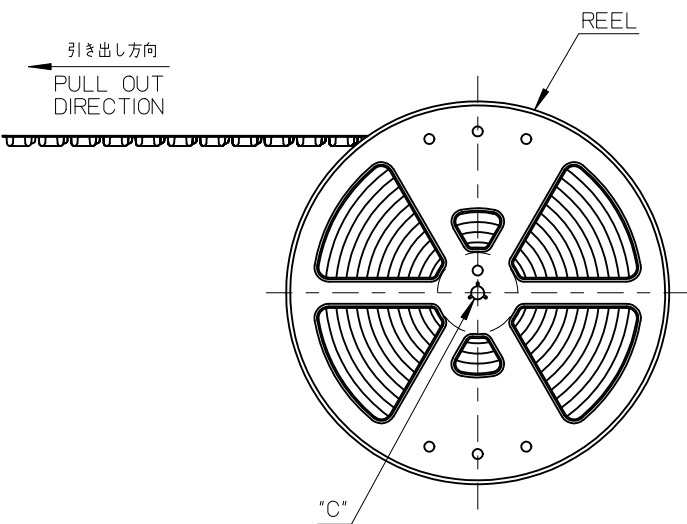
金メッキ: 0.1µm 以上
下地ニッケルメッキ: 2~6µm
FPC PATTERN PLATING
GOLD PLATING : 0.1µm MINIMUM
NICKEL UNDER PLATING : 2~6µm

*1 補強板長さが図面通り確保できない場合は、カバーレイと
補強板のオーバーラップ寸法を0.5mm以上としてください
WHEN STIFFENER BOARD DIMENSION CAN NOT
SECURE AS DRAWING, PLEASE GIVE THE OVERLAP
SIZE OF COVER FILM AND STIFFENER BOARD AS 0.5mm MINIMUM

SEE SHEET 1 OF 2	EC NO: J2011-1637	2011/05/31	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	DRW: NHIYAMOTO	2011/05/31	10 UNDER	± ---	MM ONLY			METRIC	
	CHK: DJIJIJIMA	2011/05/31	10 OVER 30 UNDER	± ---	DRAWN BY	DATE	TITLE	0.3 FPC CONN E/O BTM CONTACT TYPE HGT=0.95MM	
	APP: KMORIKAWA	2011/06/02	30 OVER	± ---	CHECKED BY	DATE			
REV	DESCRIPTION		ANGULAR	±1 °	APPROVED BY	DATE	MOLEX INCORPORATED		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.	503566-***8		DOCUMENT NO.	SD-503566-001		SHEET NO. 2 OF 2
			SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

注記 NOTES

- 製品詳細寸法については図面 SD-503566-001 を参照下さい。
RE DETAILED DIMENSION, SEE SD-503566-001
- 梱包数量：3000個/リール
NUMBER OF CONNECTORS : 3000 PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



- 材料 MATERIAL
 キャリアテープ (CARRIER TAPE) : ポリスチレン (POLYSTYRENE)
 トップテープ (TOP TAPE) : PET , PE , PEF
 リール (REEL) : ポリスチレン (PS) <リサイクル材を含む>
 POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>
- トップテープの剝離強度については、IEC60286-3に準拠
 TOP TAPE PEEL FORCE IS DEFINED BY IEC60286-3.

REVISED EC NO: J2011-1637 DRWN: HMIYAMOTO 2011/05/31 CHKD: HIJIMA 2011/05/31 APPR: KMORIKAWA 2011/06/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	MODEL NO. 503566-**00
	10 UNDER	±0.2	DRAWN BY HIJIMA	DATE 2010/05/20	TITLE 0.3 FPC CONN. E/O TAPING PACKAGE (503566-**08 SERIES)		
	10 OVER 30 UNDER	±0.25	CHECKED BY NMATSUURA	DATE 2010/05/20	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY KMORIKAWA	DATE 2010/06/11	DOCUMENT NO. SD-503566-002	SHEET NO. 1 OF 2	
	ANGULAR ±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	

F

E

D

C

B

A

F

E

D

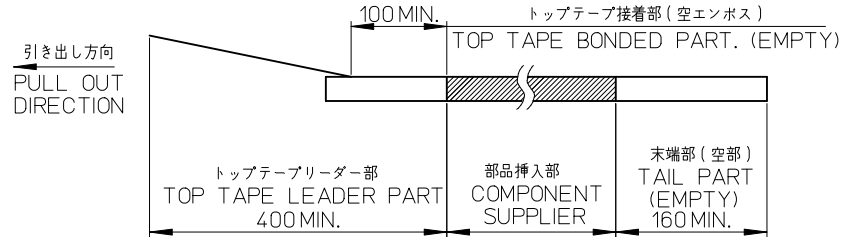
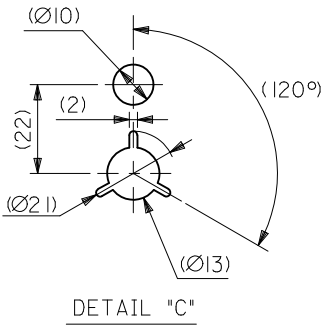
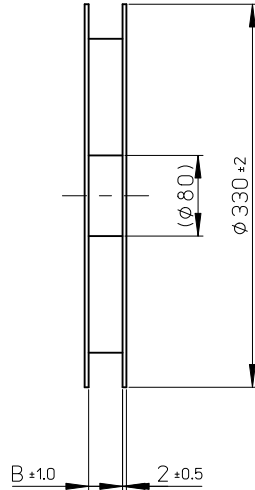
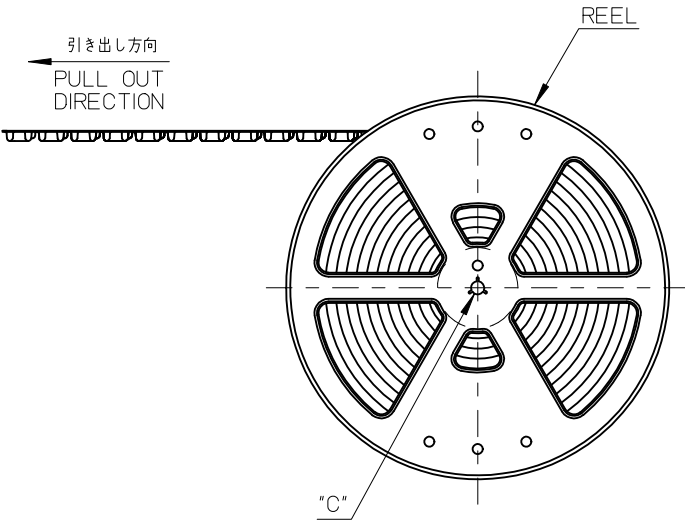
C

B

A

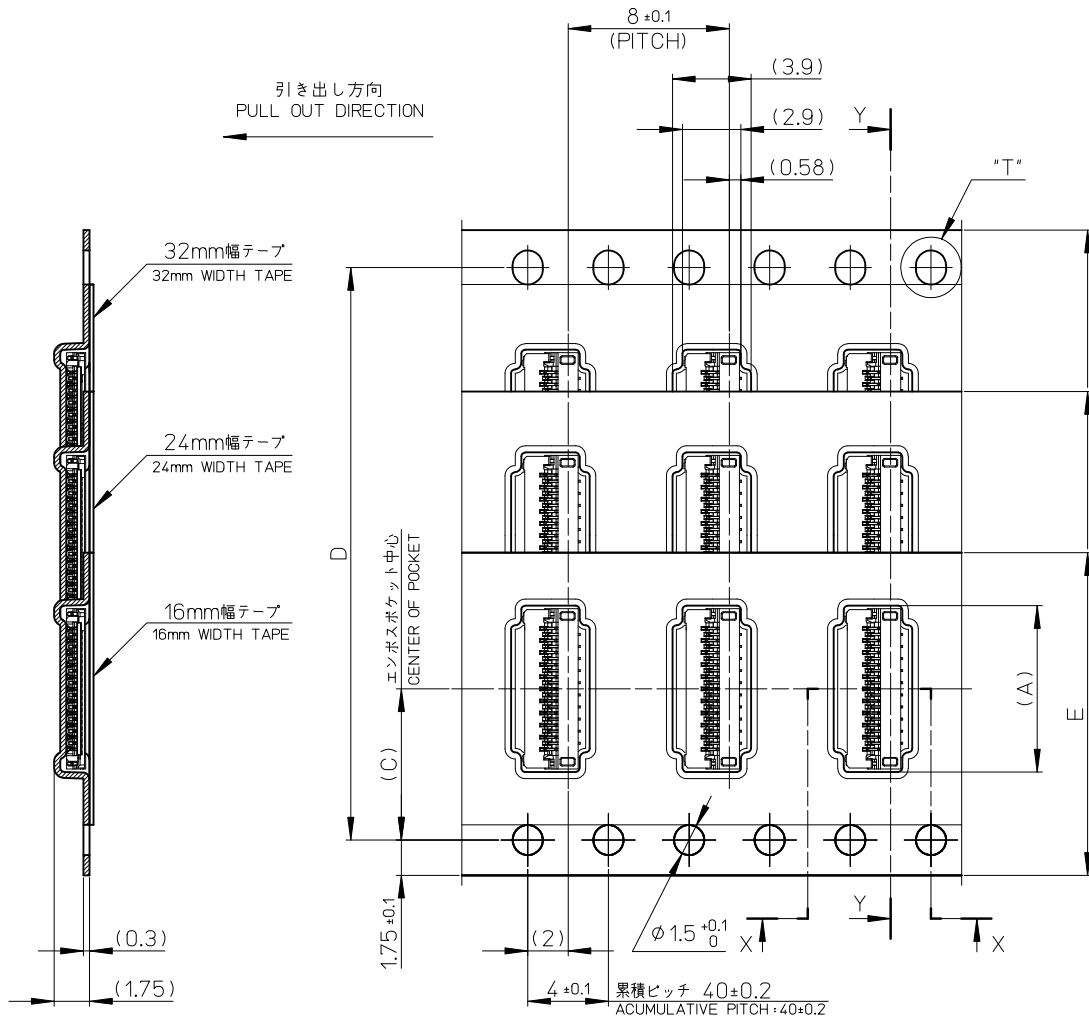
注記 NOTES

- 製品詳細寸法については図面 SD-503566-001 を参照下さい。
RE DETAILED DIMENSION, SEE SD-503566-001
- 梱包数量: 3000個/リール
NUMBER OF CONNECTORS : 3000 PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH

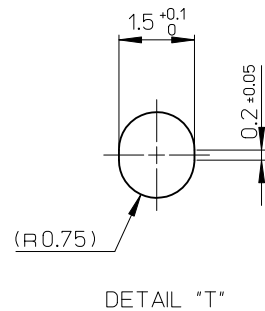


- 材料 MATERIAL
 キャリアテープ (CARRIER TAPE): ポリスチレン (POLYSTYRENE)
 トップテープ (TOP TAPE): PET, PE, PEF
 リール (REEL): ポリスチレン (PS) <リサイクル材を含む>
 POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>
- トップテープの剝離強度については、IEC60286-3に準拠
 TOP TAPE PEEL FORCE IS DEFINED BY IEC60286-3.

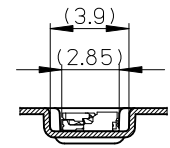
REVISED EC NO: J2011-1637 DRWN: HIYAMOTO 2011/05/31 CHKD: HIJIMA 2011/05/31 APPR: KMORIKAWA 2011/06/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	MODEL NO. 503566-**00
	10 UNDER	±0.2	DRAWN BY HIJIMA	DATE 2010/05/20	TITLE 0.3 FPC CONN. E/O TAPING PACKAGE (503566-**08 SERIES)		
	10 OVER 30 UNDER	±0.25	CHECKED BY NMATSUURA	DATE 2010/05/20	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY KMORIKAWA	DATE 2010/06/11	MATERIAL NO.	DOCUMENT NO.	SHEET NO.
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-503566-002	
				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



SECTION Y-Y



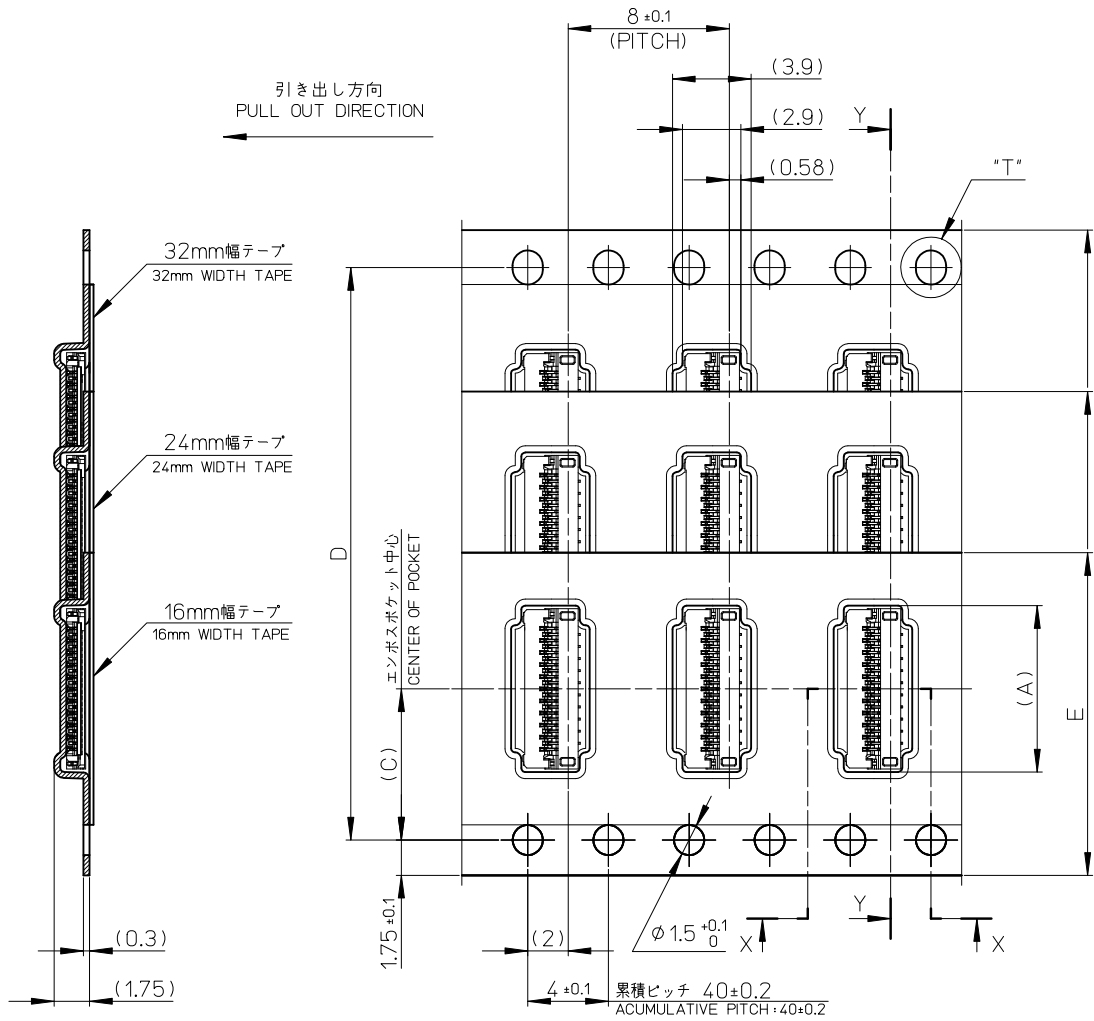
DETAIL "T"



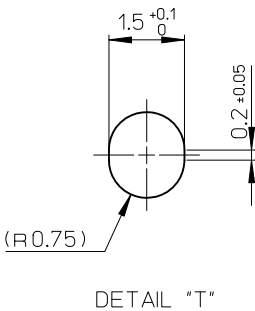
SECTION X-X

32±0.3	28.4	14.2	33.4	17.25	503566-5100	51
24±0.3	—	11.5	25.4	15.45	503566-4500	45
				14.85	503566-4300	43
				14.25	503566-4100	41
				13.65	503566-3900	39
				13.05	503566-3700	37
				12.45	503566-3500	35
				11.85	503566-3300	33
				11.25	503566-3100	31
				10.05	503566-2700	27
				16±0.3	—	7.5
8.85	503566-2300	23				
8.25	503566-2100	21				
7.65	503566-1900	19				
7.05	503566-1700	17				
6.45	503566-1500	15				
5.85	503566-1300	13				
5.25	503566-1100	11				
4.65	503566-0900	9				
E キャリアテープ幅 EMBOSSED TAPE WIDTH	D	C	B	A	EMBOSSED TAPE PACKAGE オーダー番号 ORDER NO.	極数 CIRCUITS

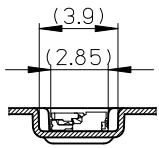
SEE SHEET 1 OF 2 EC NO: J2011-1637 DRWN: HMIYAMOTO 2011/05/31 CHKD: HIJIMA 2011/05/31 APPR: KMORIKAWA 2011/06/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY HIJIMA	DATE 2010/05/20	TITLE 0.3 FPC CONN. E/O TAPING PACKAGE (503566-**08 SERIES)		
	10 OVER 30 UNDER	±0.25	CHECKED BY NMATSUURA	DATE 2010/05/20	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY KMORIKAWA	DATE 2010/06/11	DOCUMENT NO. SD-503566-002		
	ANGULAR	±3 °	MATERIAL NO.	SEE CHART	SHEET NO. 2 OF 2		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



SECTION Y-Y



DETAIL "T"



SECTION X-X

32±0.3	28.4	14.2	33.4	17.25	503566-5100	51
24±0.3	—	11.5	25.4	15.45	503566-4500	45
				14.85	503566-4300	43
				14.25	503566-4100	41
				13.65	503566-3900	39
				13.05	503566-3700	37
				12.45	503566-3500	35
				11.85	503566-3300	33
				11.25	503566-3100	31
				10.05	503566-2700	27
				16±0.3	—	7.5
8.85	503566-2300	23				
8.25	503566-2100	21				
7.65	503566-1900	19				
7.05	503566-1700	17				
6.45	503566-1500	15				
5.85	503566-1300	13				
5.25	503566-1100	11				
4.65	503566-0900	9				
E キャリアテープ幅 EMBOSSED TAPE WIDTH	D	C	B	A	EMBOSSED TAPE PACKAGE オーダー番号 ORDER NO.	極数 CIRCUITS

SEE SHEET 1 OF 2 EC NO: J2011-1637 DRWN: HMIYAMOTO 2011/05/31 CHKD: HIJIMA 2011/05/31 APPR: KMORIKAWA 2011/06/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY HIJIMA	DATE 2010/05/20	TITLE 0.3 FPC CONN. E/O TAPING PACKAGE (503566-**08 SERIES)		
	10 OVER 30 UNDER	±0.25	CHECKED BY NMATSUURA	DATE 2010/05/20	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY KMORIKAWA	DATE 2010/06/11	DOCUMENT NO. SD-503566-002	SHEET NO. 2 OF 2	
ANGULAR	±3 °	MATERIAL NO.		SEE CHART			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							